

# 3 Volt Single Chip 12-Bit Data Acquisition System

#### **FEATURES**

- Single Supply 3.3V or ±3.3V Operation
- Software Programmable Features

   Unipolar/Bipolar Conversions
   4 Differential/8 Single-Ended Inputs
   Variable Data Word Length
   Power Shutdown
- Built-In Sample-and-Hold
- Direct 4-Wire Interface to Most MPU Serial Ports and All MPU Parallel Ports
- 25kHz Maximum Throughput Rate
- Available in 20-Lead PDIP and 20-Lead SW Packages

# **APPLICATIONS**

Minimum Guaranteed Supply Voltage: 2.7V

Resolution: 12 Bits

■ Fast Conversion Time: 26µs Max Over Temp

Low Supply Currents: 1.0mA

#### DESCRIPTION

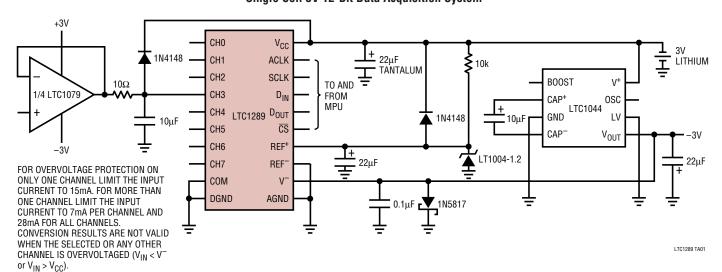
The LTC®1289 is a 3V data acquisition component which contains a serial I/O successive approximation A/D converter. The device specifications are guaranteed at a supply voltage of 2.7V. It uses LTCMOS™ switched capacitor technology to perform a 12-bit unipolar, or 11-bit plus sign bipolar A/D conversion. The 8 channel input multiplexer can be configured for either single-ended or differential inputs (or combinations thereof). An on-chip sample and hold is included for all single-ended input channels. When the LTC1289 is idle it can be powered down in applications where low power consumption is desired.

The serial I/O is designed to be compatible with industry standard full duplex serial interfaces. It allows either MSB-or LSB- first data and automatically provides 2's complement output coding in the bipolar mode. The output data word can be programmed for a length of 8, 12 or 16 bits. This allows easy interface to shift registers and a variety of processors.

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# TYPICAL APPLICATION

#### Single Cell 3V 12-Bit Data Acquisition System



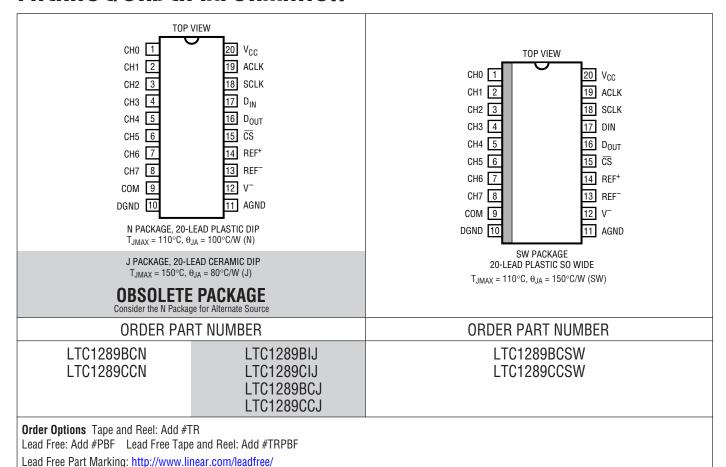


# **ABSOLUTE MAXIMUM RATINGS** (Notes 1 and 2)

Supply Voltage V <sub>CC</sub> to GND or V <sup>-</sup> 12V
Negative Supply Voltage (V <sup>-</sup> )6V to GND
Voltage
Analog and Reference Inputs $(V^{-}) - 0.3V$ to $V_{CC} + 0.3V$
Digital Inputs0.3V to 12V
Digital Outputs $-0.3V$ to $V_{CC} + 0.3V$

Power Dissipation	500mW
Operating Temperature Range	
LTC1289BC, LTC1289CC(	0°C to 70°C
Storage Temperature Range65°	°C to 150°C
Lead Temperature (Soldering, 10 sec.)	300°C

# PACKAGE/ORDER INFORMATION



Consult LTC Marketing for parts specified with wider operating temperature ranges.

# **CONVERTER AND MULTIPLEXER CHARACTERISTICS** The $\bullet$ denotes the specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^{\circ}C$ . (Note 3)

				LTC1289B					
PARAMETER	CONDITIONS		MIN	TYP	MAX	MIN	TYP	MAX	UNITS
Offset Error	V <sub>CC</sub> = 2.7V (Note 4)	•			±1.5			±1.5	LSB
Linearity Error (INL)	V <sub>CC</sub> = 2.7V (Notes 4 and 5)	•			±0.5			±0.5	LSB
Gain Error	V <sub>CC</sub> = 2.7V (Note 4)	•			±0.5			±1.0	LSB

LINEAR

# **CONVERTER AND MULTIPLEXER CHARACTERISTICS** The $\bullet$ denotes the specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^{\circ}C$ . (Note 3)

				LTC1289B			LTC1289C		
PARAMETER	CONDITIONS		MIN	TYP	MAX	MIN	TYP	MAX	UNITS
Minimum Resolution for Which No Missing Codes are Guaranteed					12			12	BITS
Analog and REF Input Range	Input Range (Note 7) $(V^{-}) - 0.05V$ to $V_{CC} + 0.05V$ $(V^{-}) - 0.05V$ to $V_{CC} + 0.05V$							+ 0.05V	V
On Channel Leakage Current (Note 8)	On Channel = 3V Off Channel = 0V	•			±1			±1	μА
,	On Channel = 0V Off Channel = 3V	•			±1			±1	μА
Off Channel Leakage Current (Note 8)	On Channel = 3V Off Channel = 0V	•			±1			±1	μА
	On Channel = 0V Off Channel = 3V	•			±1			±1	μА

# **AC CHARACTERISTICS** The $\bullet$ denotes the specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^{\circ}C$ . (Note 3)

				LTC128 LTC128		
SYMBOL	PARAMETER	CONDITIONS	MIN TYP	MAX	UNITS	
fsclk	Shift Clock Frequency	(Note 6)		0	1.0	MHz
faclk	A/D Clock Frequency	(Note 6)		(Note 10)	2.0	MHz
tacc	Delay time from $\overline{\text{CS}} \downarrow$ to D <sub>OUT</sub> Data Valid	(Note 9)		2		ACLK Cycles
tsmpl	Analog Input Sample Time	See Operating Sequence		7		SCLK Cycles
tconv	Conversion Time	See Operating Sequence		52		ACLK Cycles
tcyc	Total Cycle Time	See Operating Sequence (Note 6)		12 SCLK + 56 ACLK		Cycles
t <sub>dDO</sub>	Delay Time, SCLK↓ to D <sub>OUT</sub> Data Valid	See Test Circuits	•	200	350	ns
t <sub>dis</sub>	Delay Time, CS↑ to D <sub>OUT</sub> Hi-Z	See Test Circuits	•	70	150	ns
t <sub>en</sub>	Delay Time, 2nd ACLK↓ to D <sub>OUT</sub> Enabled	See Test Circuits	•	130	250	ns
thCS	Hold Time, CS After Last SCLK↓	(Note 6)		0		ns
thDI	Hold Time, D <sub>IN</sub> After SCLK↑	(Note 6)		50		ns
thDO	Time Output Data Remains Valid After SCLK↓			50		ns
tf	Dout Fall Time	See Test Circuits	•	40	100	ns
t <sub>r</sub>	D <sub>OUT</sub> Rise Time	See Test Circuits	•	40	100	ns
t <sub>suDI</sub>	Setup Time, D <sub>IN</sub> Stable Before SCLK↑	(Note 6 and 9)		50		ns
t <sub>su</sub> cs	Setup Time, CS↓ Before Clocking in First Address Bit	(Note 6 and 9)		2 ACLK Cycles + 180ns		
twhcs	CS High Time During Conversion	(Note 6)		52		ACLK Cycles
Cin	Input Capacitance	Analog Inputs On Channel Analog Inputs Off Channel Digital Inputs		100 5 5		pF pF pF



# **DIGITAL AND DC ELECTRICAL CHARACTERISTICS** The $\bullet$ denotes the specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^{\circ}C$ . (Note 3)

					LTC1289 LTC1289		
SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
VIH	High Level Input Voltage	Vcc = 3.6V	•	2.1			V
VIL	Low Level Input Voltage	Vcc = 3.0V	•			0.45	V
lih	High Level Input Current	VIN = VCC	•			2.5	μА
IIL	Low Level Input Current	V <sub>IN</sub> = 0V	•			-2.5	μА
Voh	High Level Output Voltage	$V_{CC} = 3.0V$ $I_0 = 20\mu A$ $I_0 = 400\mu A$	•	2.7	2.90 2.85		V
V <sub>OL</sub>	Low Level Output Voltage	$V_{CC} = 3.0V$ $I_0 = 20\mu A$ $I_0 = 400\mu A$	•		0.05 0.10	0.3	V
I <sub>OZ</sub>	High Z Output Leakage	$V_{OUT} = V_{CC}, \overline{CS}$ High $V_{OUT} = 0V, \overline{CS}$ High	•			3 -3	μA μA
ISOURCE	Output Source Current	Vout = 0V			-10		mA
Isink	Output Sink Current	Vout = Vcc			9		mA
Icc	Positive Supply Current	CS High CS High, Power Shutdown, ACLK Off	•		1.5 1.0	5 10	mA μA
I <sub>REF</sub>	Reference Current	V <sub>REF</sub> = 2.5V	•		10	50	μА
<u> -</u>	Negative Supply Current	CS High	•		1	50	μА

**Note 1:** Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

**Note 2:** All voltage values are with respect to ground with DGND, AGND and REF<sup>-</sup>wired together (unless otherwise noted).

**Note 3:**  $V_{CC} = 3V$ ,  $V_{REF} + = 2.5V$ ,  $V_{REF} - = 0V$ ,  $V^- = 0V$  for unipolar mode and -3V for bipolar mode, ACLK = 2.0MHz unless otherwise specified.

**Note 4:** These specs apply for both unipolar and bipolar modes. In bipolar mode, one LSB is equal to the bipolar input span  $(2V_{REF})$  divided by 4096. For example, when  $V_{REF} = 2.5V$ , 1LSB(bipolar) = 2(2.5)/4096 = 1.22mV.  $V^- = -2.7V$  for bipolar mode.

**Note 5:** Integral nonlinearity is defined as the deviation of a code from a straight line passing through the actual endpoints of the transfer curve. The deviation is measured from the center of the quantization band.

Note 6: Recommended operating conditions.

**Note 7:** Two on-chip diodes are tied to each analog input which will conduct for analog voltages one diode drop below GND or one diode drop above  $V_{CC}$ . Be careful during testing at low  $V_{CC}$  levels, as high level analog inputs can cause this input diode to conduct, especially at elevated temperature, and cause errors for inputs near full scale. This spec allows 50mV forward bias of either diode. This means that as long as the analog input does not exceed the supply voltage by more than 50mV, the output code will be correct.

Note 8: Channel leakage current is measured after the channel selection.

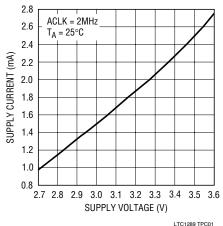
**Note 9:** To minimize errors caused by noise at the chip select input, the internal circuitry waits for two ACLK falling edges after a chip select falling edge is detected before responding to control input signals. Therefore, no attempt should be made to clock an address in or data out until the minimum chip select set-up time has elasped. See Typical Peformance Characteristics curves for additional information  $(t_{su}\overline{cs}\ vs\ V_{CC})$ .

**Note 10:** Increased leakage currents at elevated temperatures cause the S/H to droop, therefore it's recommended that  $f_{ACLK} \ge 125$ kHz at  $85^{\circ}$ C and  $f_{ACLK} \ge 15$ kHz at  $25^{\circ}$ C.

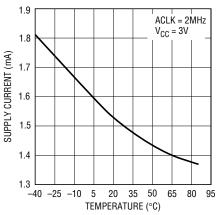
LINEAR TECHNOLOGY

# TYPICAL PERFORMANCE CHARACTERISTICS

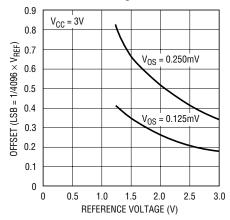
### Supply Current vs Supply Voltage



#### **Supply Current vs Temperature**

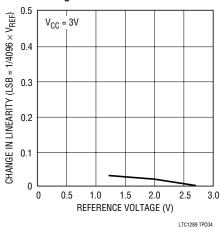


#### Unadjusted Offset Voltage vs Reference Voltage

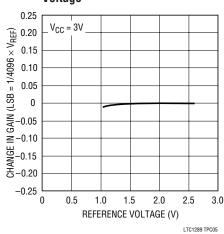


LTC1289 TPC03

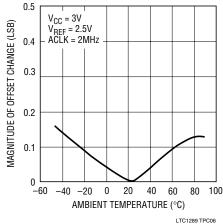
#### Change in Linearity vs Reference Voltage



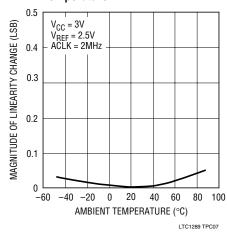
#### Change in Gain vs Reference Voltage



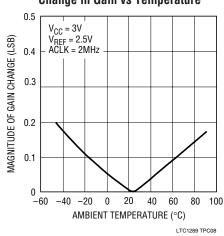
#### Change in Offset vs Temperature



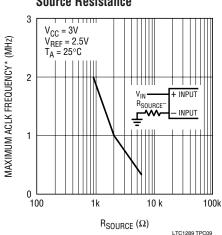
#### Change in Linearity vs Temperature



#### Change in Gain vs Temperature



#### Maximum ACLK Frequency vs **Source Resistance**

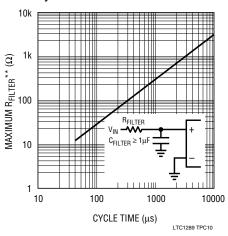


\* MAXIMUM ACLK FREQUENCY REPRESENTS THE ACLK FREQUENCY AT WHICH A 0.1LSB SHIFT IN THE ERROR AT ANY CODE TRANSITION FROM ITS 2MHZ VALUE IS FIRST DETECTED.

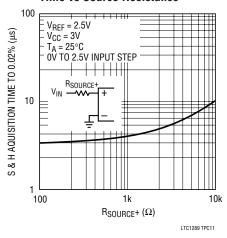


# TYPICAL PERFORMANCE CHARACTERISTICS

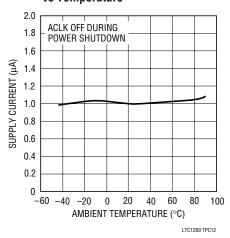
#### Maximum Filter Resistor vs Cycle Time



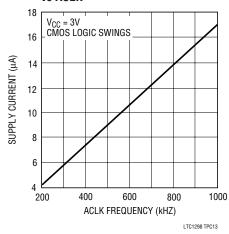
#### Sample and Hold Acquisition Time vs Source Resistance



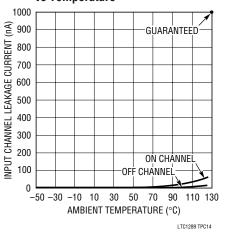
# Supply Current (Power Shutdown) vs Temperature



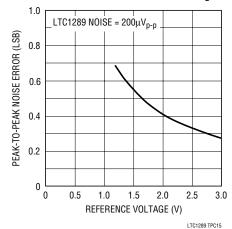
# Supply Current (Power Shutdown) vs ACLK



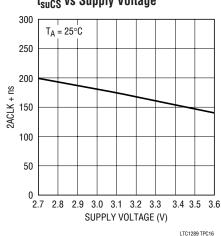
# Input Channel Leakage Current vs Temperature



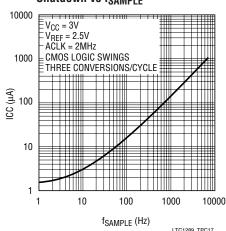
Noise Error vs Reference Voltage



### t<sub>suCS</sub> vs Supply Voltage



# Power Consumption with Power Shutdown vs f<sub>SAMPLE</sub>



<sup>\*\*</sup> MAXIMUM R<sub>FILTER</sub> REPRESENTS THE FILTER RESISTOR VALUE AT WHICH A 0.1LSB CHANGE IN FULL SCALE ERROR FROM ITS VALUE AT R<sub>FILTER</sub> = 0 IS FIRST DETECTED.



# PIN FUNCTIONS

**CHO – CH7 (Pins 1 – 8):** Analog Inputs. The analog inputs must be free of noise with respect to AGND.

**COM (Pin 9):** Common. The common pin defines the zero reference point for all single-ended inputs. It must be free of noise and is usually tied to the analog ground plane.

**DGND (Pin 10):** Digital Ground. This is the ground for the internal logic. Tie to the ground plane.

**AGND (Pin 11):** Analog Ground. AGND should be tied directly to the analog ground plane.

**V**<sup>-</sup>(**Pin 12**): Negative Supply. Tie V<sup>-</sup> to the most negative potential in the circuit. (Ground in single supply applications.)

**REF**<sup>-</sup>, **REF**<sup>+</sup> (**Pins 13,14**) Reference Inputs. The reference inputs must be kept free of noise with respect to AGND.

**CS** (**Pin 15**): Chip Select Input. A logic low on this input enables data transfer.

**D**<sub>OUT</sub> (**Pin 16**): Digital Data Output. The A/D conversion result is shifted out of this output.

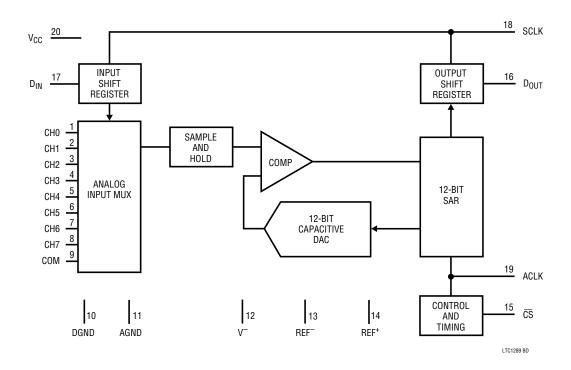
 $D_{IN}$  (Pin 17): Digital Input. The A/D configuration word is shifted into this input.

**SCLK (Pin 18):** Shift Clock. This clock synchronizes the serial data transfer.

**ACLK (Pin 19):** A/D Conversion Clock. This clock controls the A/D conversion process.

**V<sub>CC</sub>** (**Pin 20**): Positive Supply. This supply must be kept free of noise and ripple by bypassing directly to the analog ground plane.

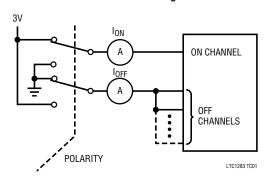
## **BLOCK DIAGRAM**



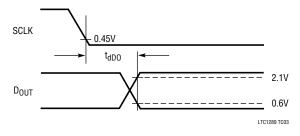


# **TEST CIRCUITS**

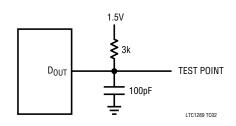
#### On and Off Channel Leakage Current



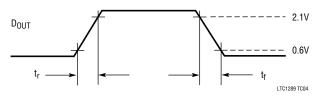
### Voltage Waveforms for $D_{OUT}$ Delay Time, $t_{dDO}$



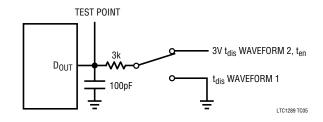
Load Circuit for  $t_{dDO}$ ,  $t_{r}$  and  $t_{f}$ 



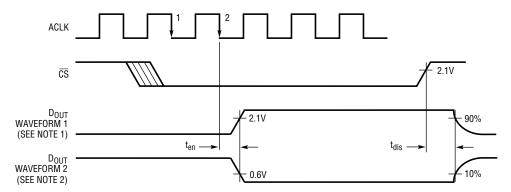
Voltage Waveforms for Dout Rise and Fall Times, tr,tf



Load Circuit for t<sub>dis</sub> and t<sub>en</sub>



#### Voltage Waveforms for ten and tdis



**NOTE 1:** WAVEFORM 1 IS FOR AN OUTPUT WITH CONDITIONS SUCH THAT THE OUTPUT IS HIGH UNLESS DISABLED BY THE OUTPUT CONTROL. **NOTE 2:** WAVEFORM 2 IS FOR AN OUTPUT WITH INTERNAL CONDITIONS SUCH THAT THE OUTPUT

**NOTE 2:** WAVEFORM 2 IS FOR AN OUTPUT WITH INTERNAL CONDITIONS SUCH THAT THE OUTPUT IS LOW UNLESS DISABLED BY THE OUTPUT CONTROL.

LTC1289 TC06



The LTC1289 is a data acquisition component which contains the following functional blocks:

- 1. 12-bit successive approximation capacitive A/D converter
- 2. Analog multiplexer (MUX)
- 3. Sample-and-hold (S/H)
- 4. Synchronous, full duplex serial interface
- 5. Control and timing logic

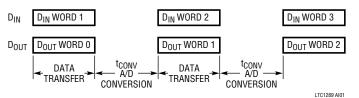
#### **DIGITAL CONSIDERATIONS**

#### **Serial Interface**

The LTC1289 communicates with microprocessors and other external circuitry via a synchronous, full duplex, four wire serial interface (see Operating Sequence). The shift clock (SCLK) synchronizes the data transfer with each bit being transmitted on the falling SCLK edge and captured on the rising SCLK edge in both transmitting and receiving systems. The data is transmitted and received simultaneously (full duplex).

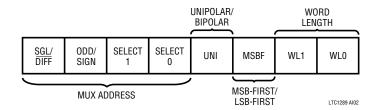
Data transfer is initiated by a falling chip select (CS) signal. After the falling  $\overline{\text{CS}}$  is recognized, an 8-bit input word is shifted into the D<sub>IN</sub> input which configures the LTC1289 for the next conversion. Simultaneously, the result of the

previous conversion is output on the  $D_{OUT}$  line. At the end of the data exchange the requested conversion begins and  $\overline{CS}$  should be brought high. After  $t_{CONV}$ , the conversion is complete and the results will be available on the next data transfer cycle. As shown below, the result of a conversion is delayed by one  $\overline{CS}$  cycle from the input word requesting it

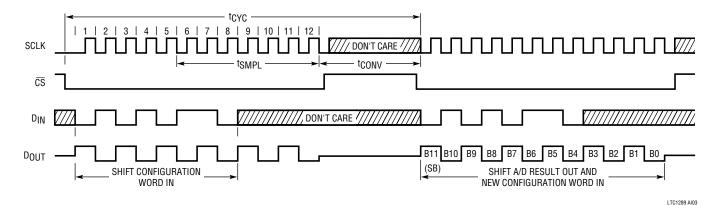


#### **Input Data Word**

The LTC1289 8-bit data word is clocked into the  $D_{IN}$  input on the first eight rising SCLK edges after chip select is recognized. Further inputs on the  $D_{IN}$  pin are then ignored until the next  $\overline{CS}$  cycle. The eight bits of the input word are defined as follows:



# Operating Sequence (Example: Differential Inputs (CH3-CH2), Bipolar, MSB-First and 12-Bit Word Length)





#### **MUX Address**

The first four bits of the input word assign the MUX configuration for the requested conversion. For a given channel selection, the converter will measure the voltage between the two channels indicated by the + and - signs in the selected row of Table 1. Note that in differential

mode (SGL/ $\overline{\text{DIFF}}$  = 0) measurements are limited to four adjacent input pairs with either polarity. In single-ended mode, all input channels are measured with respect to COM.

**Table 1. Multiplexer Channel Selection** 

MU	MUX ADDRESS				DIFFERENTIAL CHANNEL SELECTION							M	UX ADD	RESS		SING	LE-E	NDED	CHA	NNEL	SELE	CTIO	N
SGL/ DIFF	ODD SIGN	SEL 1	ECT 0	0	1	2	3	4	5	6	7	SGL/ DIFF	ODD SIGN	SELECT 1 0	0	1	2	3	4	5	6	7	СОМ
0	0	0	0	+	_							1	0	0 0	+								_
0	0	0	1			+	_					1	0	0 1			+						_
0	0	1	0					+	_			1	0	1 0					+				_
0	0	1	1							+	_	1	0	1 1							+		_
0	1	0	0	_	+							1	1	0 0		+							_
0	1	0	1			_	+					1	1	0 1				+					_
0	1	1	0					-	+			1	1	1 0						+			_
0	1	1	1							_	+	1	1	1 1								+	_

# 

#### Changing the MUX Assignment "On the Fly"

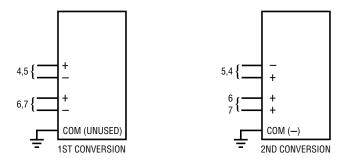


Figure 1. Examples of Multiplexer Options on the LTC1289

LTC1289 AIF01



### Unipolar/Bipolar (UNI)

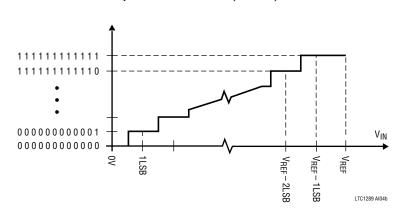
The fifth input bit (UNI) determines whether the conversion will be unipolar or bipolar. When UNI is a logical one, a unipolar conversion will be performed on the selected

input voltage. When UNI is a logical zero, a bipolar conversion will result. The input span and code assignment for each conversion type are shown in the figures below.

#### Unipolar Output Code (UNI = 1)

OUTPUT CODE	INPUT VOLTAGE	INPUT VOLTAGE (V <sub>REF</sub> = 2.5V)
111111111111111111111111111111111111111	V <sub>REF</sub> − 1LSB V <sub>REF</sub> − 2LSB •	2.4994V 2.4988V
•	•	•
0000000000001	1LSB 0V	0.0006V 0V
		I TC1289 AI04

#### Unipolar Transfer Curve (UNI = 1)

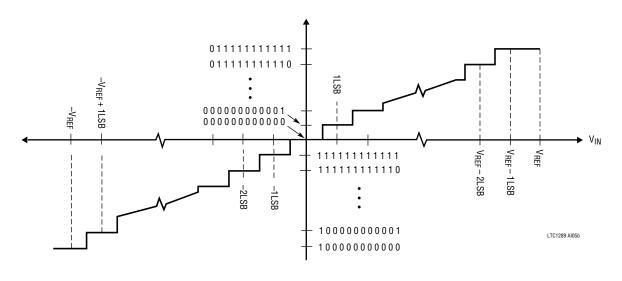


#### Bipolar Output Code (UNI = 0)

OUTPUT CODE	INPUT VOLTAGE	INPUT VOLTAGE (V <sub>REF</sub> = 2.5V)	OUTPUT CODE	INPUT VOLTAGE	INPUT VOLTAGE (V <sub>REF</sub> = 2.5V)
011111111111	V <sub>REF</sub> – 1LSB V <sub>REF</sub> – 2LSB	2.4988V 2.4976V	1111111111111	−1LSB −2LSB	-0.0012V -0.0024V
			•		
0000000000001	1LSB 0V	0.0012V 0V	1000000000001	–(V <sub>REF</sub> ) + 1LSB – (V <sub>REF</sub> )	-2.4988V -2.5000V

LTC1289 AI05a

#### Bipolar Transfer Curve (UNI = 0)



The following discussion will demonstrate how the two reference pins are to be used in conjunction with the analog input multiplexer. In unipolar mode the input span of the A/D is set by the difference in voltage on the REF+ pin and the REF- pin. In the bipolar mode the input span is twice the difference in voltage on the REF+ pin and the REF- pin. In the unipolar mode the lower value of the input span is set by the voltage on the COM pin for single-ended inputs and by the voltage on the minus input pin for differential inputs. For the bipolar mode of operation the voltage on the COM pin or the minus input pin sets the center of the input span.

The upper and lower value of the input span can now be summarized in the following table:

INPUT CONFIGURATION	ON	UNIPOLAR MODE	BIPOLAR MODE
	Lower Value Upper Value	COM (REF <sup>+</sup> – REF <sup>-</sup> ) + COM	-(REF <sup>+</sup> - REF <sup>-</sup> ) + COM (REF <sup>+</sup> - REF <sup>-</sup> ) + COM
	Lower Value Upper Value		-(REF <sup>+</sup> - REF <sup>-</sup> ) + IN <sup>-</sup> (REF <sup>+</sup> - REF <sup>-</sup> ) + IN <sup>-</sup>

The reference voltages REF $^+$  and REF $^-$  can fall between V $_{CC}$  and V $^-$ , but the difference (REF $^+$  $^-$ REF $^-$ ) must be less than or equal to V $_{CC}$ . The input voltages must be less than or equal to V $_{CC}$  and greater than or equal to V $^-$ .

The following examples are for a single-ended input configuration.

**Example 1:** Let  $V_{CC} = 3.3V$ ,  $V^- = 0V$ ,  $REF^+ = 3V$ ,  $REF^- = 1V$  and COM = 0V. Unipolar mode of operation. The resulting input span is  $0V \le IN^+ \le 2V$ .

**Example 2:** The same conditions as Example 1 except COM = 1V. The resulting input span is  $1V \le IN^+ \le 3V$ . Note if  $IN^+ \ge 3V$  the resulting  $D_{OUT}$  word is all 1's. If  $IN^+ \le 1V$  then the resulting  $D_{OUT}$  word is all 0's.

**Example 3:** Let  $V_{CC} = 3.3V$ ,  $V^- = -3.3V$ , REF<sup>+</sup> = 3V, REF<sup>-</sup> = 1V and COM = 1V. Bipolar mode of operation. The resulting input span is  $-1V \le IN+ \le 3V$ .

For differential input configurations with the same conditions as in the above three examples the resulting input spans are as follows:

Example 1 (Diff.):  $IN^- \le IN^+ \le IN^- + 2V$ 

Example 2 (Diff.):  $IN^- \le IN^+ \le IN^- + 2V$ 

Example 3 (Diff.):  $IN^- - 2V \le IN^+ \le IN^- + 2V$ .

#### MSB-First/LSB-First Format (MSBF)

The output data of the LTC1289 is programmed for MSB-first or LSB-first sequence using the MSBF bit. For MSB-first output data, the input word clocked to the LTC1289 should always contain a logical one in the sixth bit location (MSBF bit). Likewise for LSB-first output data the input word clocked to the LTC1289 should always contain a zero in the MSBF bit location. The MSBF bit affects only the order of the output data word. The order of the input word is unaffected by this bit.

MSBF	OUTPUT FORMAT
0	LSB-First
1	MSB-First

LTC1289 AI06

### Word Length (WL1, WL0) and Power Shutdown

The last two bits of the input word (WL1 and WL0) program the output data word length and the power shutdown feature of the LTC1289. Word lengths of 8, 12 or 16 bits can be selected according to the following table.

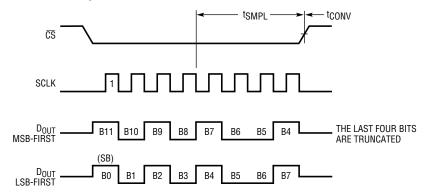
WL1	WL0	OUTPUT WORD LENGTH
0	0	8 Bits
0	1	Power Shutdown
1	0	12 Bits
1	1	16 Bits

LTC1289 AI07

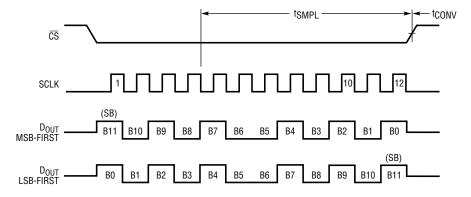
The WL1 and WL0 bits in a given  $D_{IN}$  word control the length of the present, not the next,  $D_{OUT}$  word. WL1 and WL0 are never "don't cares" and must be set for the correct  $D_{OUT}$  word length even when a "dummy"  $D_{IN}$  word is sent. On any transfer cycle, the word length should be made equal to the number of SCLK cycles sent by the MPU. Power down will occur when WL1 = 0 and WL0 = 1 is selected. The previous result will be clocked out as a 10 bit word so a "dummy" conversion is required before powering down the LTC1289. Conversions are resumed once  $\overline{CS}$  goes low or an SCLK is applied, if  $\overline{CS}$  is already low.

INEAD

#### 8-Bit Word Length



#### 12-Bit Word Length



#### 16-Bit Word Length

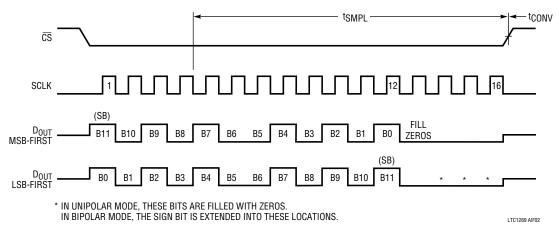


Figure 2. Data Output (D<sub>OUT</sub>) Timing with Different Word Lengths

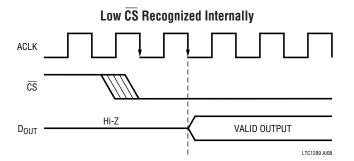


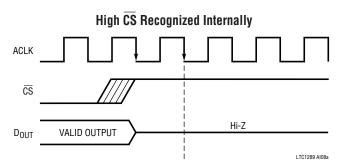
#### **Deglitcher**

A deglitching circuit has been added to the Chip Select input of the LTC1289 to minimize the effects of errors caused by noise on that input. This circuit ignores changes in state on the  $\overline{\text{CS}}$  input that are shorter in duration than one ACLK cycle. After a change of state on the  $\overline{\text{CS}}$  input, the LTC1289 waits for two falling edge of the ACLK before recognizing a valid chip select. One indication of  $\overline{\text{CS}}$  recognition is the D<sub>OUT</sub> line becoming active (leaving the Hi-Z state). Note that the deglitching applies to both the rising and falling  $\overline{\text{CS}}$  edges.

#### **CS** Low During Conversion

In the normal mode of operation,  $\overline{CS}$  is brought high during the conversion time. The serial port ignores any SCLK activity while  $\overline{CS}$  is high. The LTC1289 will also operate with  $\overline{CS}$  low during the conversion. In this mode, SCLK must remain low during the conversion as shown in the following figure. After the conversion is complete, the D<sub>OUT</sub> line will become active with the first output bit. Then the data transfer can begin as normal.





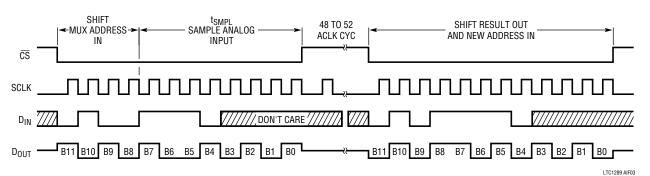


Figure 3. CS High During Conversion

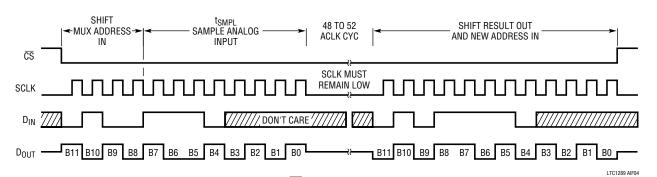


Figure 4. CS Low During Conversion



#### **Logic Levels**

The logic level standards for this supply range have not been well defined. What standards that do exist are not universally accepted. The trip point on the logic inputs of the LTC1289 is  $0.28 \times V_{CC}$ . This makes the logic inputs compatible with HC type logic levels and processors that are specified at 3.3V. The output  $D_{OUT}$  is also compatible with the above standards. The following summarizes such levels.

V <sub>OH</sub> (no load)	V <sub>CC</sub> - 0.1V
V <sub>OL</sub> (no load)	0.1V
$V_{OH}$	$0.9 \times V_{CC}$
$V_{OL}$	$0.1 \times V_{CC}$
$V_{IH}$	$0.7 \times V_{CC}$
$V_IL$	$0.2 \times V_{CC}$

The LTC1289 can be driven with 5V logic even when  $V_{CC}$  is at 3.3V. This is due to a unique input protection device that is found on the LTC1289.

#### **Microprocessor Interfaces**

The LTC1289 can interface directly (without external hardware) to most popular microprocessor (MPU) synchronous serial formats. If an MPU without a serial interface is used, then four of the MPU's parallel port lines can be programmed to form the serial link to the LTC1289. Many of the popular MPU's can operate with 3V supplies. For example the MC68HC11 is an MPU with a serial format (SPI). Likewise parallel MPU's that have the 8051 type architecture are also capable of operating at this voltage

range. The code for these processors remains the same and can be found in the LTC1290 datasheet or application notes AN36A and AN36B.

#### **Sharing the Serial Interface**

The LTC1289 can share 3-wire serial interface with other peripheral components or other LTC1289s (See Figure 5). In this case, the  $\overline{\text{CS}}$  signals decide which LTC1289 is being addressed by the MPU.

#### ANALOG CONSIDERATIONS

#### 1. Grounding

The LTC1289 should be used with an analog ground plane and single point grounding techniques.

Pin 11 (AGND) should be tied directly to this ground plane.

Pin 10 (DGND) can also be tied directly to this ground plane because minimal digital noise is generated within the chip itself.

Pin  $20(V_{CC})$  should be bypassed to the ground plane with a  $22\mu F$  tantalum with leads as short as possible. Pin  $12(V^-)$  should be bypassed with a  $0.1\mu F$  ceramic disk. For single supply applications,  $V^-$  can be tied to the ground plane.

It is also recommended that pin 13 (REF<sup>-</sup>) and pin 9 (COM) be tied directly to the ground plane. All analog inputs should be referenced directly to the single point ground. Digital inputs and outputs should be shielded from and/or routed away from the reference and analog circuitry.

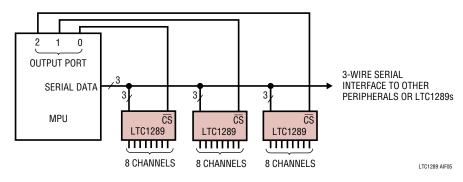


Figure 5. Several LTC1289s Sharing One 3-Wire Serial Interface



Figure 6 shows an example of an ideal ground plane design for a two-sided board. Of course, this much ground plane will not always be possible, but users should strive to get as close to this ideal as possible.

#### 2. Bypassing

For good performance, V<sub>CC</sub> must be free of noise and ripple. Any changes in the V<sub>CC</sub> voltage with respect to analog ground during a conversion cycle can induce errors or noise in the output code.  $V_{CC}$  noise and ripple can be kept below 0.5mV by bypassing the  $V_{CC}$  pin directly to the analog ground plane with a 22µF tantalum capacitor and leads as short as possible. The lead from the device to the V<sub>CC</sub> supply should also be kept to a minimum and the V<sub>CC</sub> supply should have a low output impedance such as that obtained from a voltage regulator (e.g., LT1117). Using a battery to power the LTC1289 will help reduce the amount of bypass capacitance required on the V<sub>CC</sub> pin. A battery placed close to the device will only require 10µF to adequately bypass the supply pin. Figure 7 shows the effect of poor V<sub>CC</sub> bypassing. Figure 8a shows the settling of a LT1117 low dropout regulator with a 22µF bypass

O.1µF

O.1µF

TANTALUM

O.1µF

TANTALUM

O.1µF

GROUND

PLANE

LTC1289 AIF06

Figure 6. Example Ground Plane for the LTC1289

capacitor. The noise and ripple is approximately 0.5 mV. Figure 8b shows the response of a lithium battery with a  $10 \mu\text{F}$  bypass capacitor. The noise and ripple is kept below 0.5 mV.

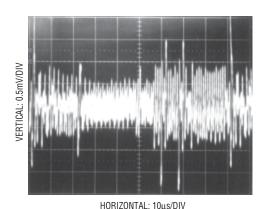
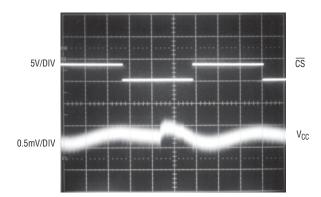


Figure 7. Poor V<sub>CC</sub> Bypassing. Noise and Ripple Can Cause A/D Errors.



HORIZONTAL:  $20\mu s/DIV$  Figure 8a. LT1117 Regulator with 22 $\mu F$  Bypassing on  $V_{CC}$ 

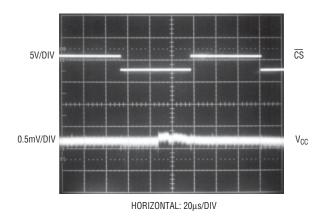


Figure 8b. Lithium Battery with 10 $\mu$ F Bypassing on  $V_{CC}$ 

LINEAR

#### 3. Analog Inputs

Because of the capacitive redistribution A/D conversion techniques used, the analog inputs of the LTC1289 have capacitive switching input current spikes. These current spikes settle quickly and do not cause a problem. However, if large source resistances are used or if slow settling op amps drive the inputs, care must be taken to insure that the transients caused by the current spikes settle completely before the conversion begins.

#### **Source Resistance**

The analog inputs of the LTC1289 look like a 100pF capacitor ( $C_{IN}$ ) is series with a 1500 $\Omega$  resistor ( $R_{ON}$ ) as shown in Figure 9. This value for  $R_{ON}$  is for  $V_{CC}=2.7V$ . With larger supply voltages  $R_{ON}$  will be reduced. For example with  $V_{CC}=2.7V$  and  $V^-=-2.7V$   $R_{ON}$  becomes 500 $\Omega$ .  $C_{IN}$  gets switched between the selected "+" and "-" inputs once during each conversion cycle. Large external source resistors and capacitances will slow the settling of

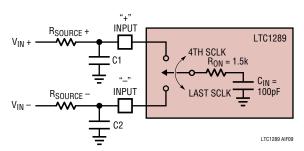


Figure 9. Analog Input Equivalent Circuit

the inputs. It is important that the overall RC time constants be short enough to allow the analog inputs to completely settle within the allotted time.

#### "+" Input Settling

This input capacitor is switched onto the "+" input during the sample phase ( $t_{SMPL}$ , see Figure 10). The sample phase starts at the 4th SCLK cycle and lasts until the falling edge of the last SCLK (the 8th, 12th or 16th SCLK cycle depending on the selected word length). The voltage on the "+" input must settle completely within this sample time. Minimizing  $R_{SOURCE}^+$  and C1 will improve the input settling time. If large "+" input source resistance must be used, the sample time can be increased by using a slower SCLK frequency or selecting a longer word length. With the minimum possible sample time of  $4\mu s$ ,  $R_{SOURCE}^+ < 2k$  and C1 < 20pF will provide adequate settling.

#### "-" Input Settling

At the end of the sample phase the input capacitor switches to the "-" input and the conversion starts (see Figure 10). During the conversion, the "+" input voltage is effectively "held" by the sample and hold and will not affect the conversion result. However, it is critical that the "-" input voltage be free of noise and settle completely during the first four ACLK cycles of the conversion time. Minimizing R<sub>SOURCE</sub> and C2 will improve settling time. If large "-" input source resistance must be used, the time allowed for

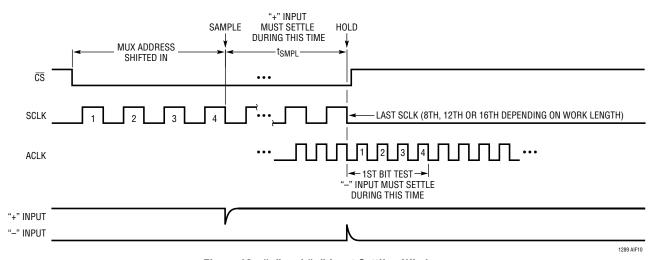


Figure 10. "+" and "-" Input Settling Windows





settling can be extended by using a slower ACLK frequency. At the maximum ACLK rate of 2MHz,  $R_{SOURCE}^-$  < 200 $\Omega$  and C2 < 20pF will provide adequate settling.

#### **Input Op Amps**

When driving the analog inputs with an op amp it is important that the op amp settle within the allowed time (see Figure 10). Again, the "+" and "-" input sampling times can be extended as described above to accommodate slower op amps. For single supply low voltage applications the LT1006, LT1013 and LT1014 can be made to settle well even with the minimum settling windows of  $4\mu s$  ("+" input) and  $2\mu s$  ("-" input) which occur at the maximum clock rates (ACLK = 2MHz and SCLK = 1MHz). Figures 11 and 12 show examples of adequate and poor op amp settling. The LT1077, LT1078 or LT1079 can be used here to reduce power consumption. Placing an RC network at the output of the op amps will improve the settling response and also reduce the broadband noise.

#### **RC Input Filtering**

It is possible to filter the inputs with an RC network as shown in Figure 13. For large values of  $C_F$  (e.g.,  $1\mu F$ ), the capacitive input switching currents are averaged into a net DC current. Therefore, a filter should be chosen with a small resistor and large capacitor to prevent DC drops across the resistor. The magnitude of the DC current is approximately  $I_{DC}=100 pF\times V_{IN}/t_{CYC}$  and is roughly proportional to  $V_{IN}.$  When running at the minimum cycle time of  $40\mu s$ , the input current equals  $6.3\mu A$  at  $V_{IN}=2.5V.$  In this case, a filter resistor of  $10\Omega$  will cause 0.1LSB of full-scale error. If a larger filter resistor must be used, errors can be eliminated by increasing the cycle time as shown in the typical curve of Maximum Filter Resistor vs Cycle Time.

#### Input Leakage Current

Input leakage currents can also create errors if the source resistance gets too large. For instance, the maximum input leakage specification of  $1\mu A$  (at  $85^{\circ}C$ ) flowing through a source resistance of  $1k\Omega$  will cause a voltage drop of 1mV or 1.6LSB with  $V_{REF}=2.5V$ . This error will be much reduced at lower temperatures because leakage drops

rapidly (see typical curve of Input Channel Leakage Current vs Temperature).

#### **Noise Coupling Into Inputs**

High source resistance input signals (>500 $\Omega$ ) are more sensitive to coupling from external sources. It is preferable to use channels near the center of the package (i.e., CH2-CH7) for signals which have the highest output resistance because they are essentially shielded by the

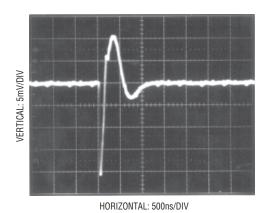


Figure 11. Adequate Settling of Op Amps Driving Analog Input

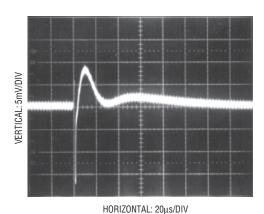


Figure 12. Poor Op Amp Settling Can Cause A/D Errors

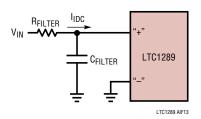


Figure 13. RC Input Filtering



pins on the package ends (DGND and CH0). Grounding any unused inputs (especially the end pin, CH0) will also reduce outside coupling into high source resistances.

#### 4. Sample and Hold

#### Single-Ended Inputs

The LTC1289 provides a built-in sample and hold (S&H) function for all signals acquired in the single-ended mode (COM pin grounded). This sample and hold allows the LTC1289 to convert rapidly varying signals (see typical curve of S&H Acquisition Time vs Source Resistance). The input voltage is sampled during the  $t_{SMPL}$  time as shown in Figure 10. The sampling interval begins after the fourth MUX address bit is shifted in and continues during the remainder of the data transfer. On the falling edge of the final SCLK, the S&H goes into hold mode and the conversion begins. The voltage will be held on either the 8th, 12th or 16th falling edge of the SCLK depending on the word length selected.

#### **Differential Inputs**

With differential inputs or when the COM pin is not tied to ground, the A/D no longer converts just a single voltage but rather the difference between two voltages. In these cases, the voltage on the selected "+" input is still sampled and held and therefore may be rapidly time varing just as in single ended mode. However, the voltage on the selected "—" input must remain constant and be free of noise and ripple throughout the conversion time. Otherwise, the differencing operation may not be performed accurately. The conversion time is 52 ACLK cycles. Therefore, a change in the "—" input voltage during this interval can cause conversion errors. For a sinusoidal voltage on the "—" input this error would be:

$$V_{\text{ERROR (MAX)}} = V_{\text{PEAK}} \times 2 \times \pi \times f(\text{"-"}) \times \frac{52}{f_{\text{ACLK}}}$$

Where f("-") is the frequency of the "-" input voltage,  $V_{PEAK}$  is its peak amplitude and  $f_{ACLK}$  is the frequency of the ACLK. In most cases  $V_{ERBOR}$  will not be significant. For

a 60Hz signal on the "–" input to generate a 1/4LSB error (150 $\mu$ V) with the converter running at ACLK = 2MHz, its peak value would have to be 15mV.

#### 5. Reference Inputs

The voltage between the reference inputs of the LTC1289 defines the voltage span of the A/D converter. The reference inputs will have transient capacitive switching currents due to the switched capacitor conversion technique (see Figure 14). During each bit test of the conversion (every 4 ACLK cycles), a capacitive current spike will be generated on the reference pins by the A/D. These current spikes settle quickly and do not cause a problem. However, if slow settling circuitry is used to drive the reference inputs, care must be taken to insure that transients caused by these current spikes settle completely during each bit test of the conversion.

When driving the reference inputs, two things should be kept in mind:

1. Transients on the reference inputs caused by the capacitive switching currents must settle completely during each bit test (each 4 ACLK cycles). Figures 15 and 16 show examples of both adequate and poor settling. Using a slower ACLK will allow more time for the reference to settle. However, even at the maximum ACLK rate of 2MHz most references and op amps can be made to settle within the 2μs bit time. For example an LT1019 used in the shunt mode with a 10μF bypass capacitor will settle adequately. To minimize power an LT1004-2.5 can be used with a 10μF bypass capacitor. For lower value references the LT1004-1.2 with a 1μF bypass capacitor can be used.

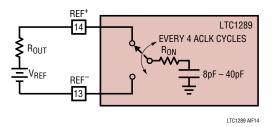


Figure 14. Reference Input Equivalent Circuit



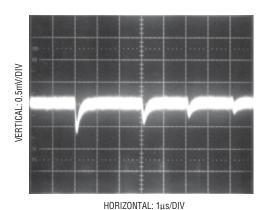
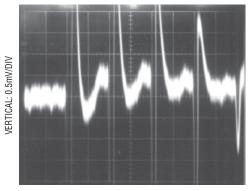


Figure 15. Adequate Reference Settling



HORIZONTAL: 1µs/DIV

Figure 16. Poor Reference Settling Can Cause A/D Errors

 It is recommended that REF<sup>-</sup> input be tied directly to the analog ground plane. If REF<sup>-</sup> is biased at a voltage other than ground, the voltage must not change during a conversion cycle. This voltage must also be free of noise and ripple with respect to analog ground.

#### 6. Reduced Reference Operation

The effective resolution of the LTC1289 can be increased by reducing the input span of the converter. The LTC1289 exhibits good linearity and gain over a wide range of reference voltages (see typical curves of Linearity and Gain Error vs Reference Voltage). However, care must be taken when operating at low values of  $V_{REF}$  because of the reduced LSB step size and the resulting higher accuracy requirement placed on the converter. The following factors must be considered when operating at low  $V_{REF}$  values:

- 1. Offset
- 2. Noise

#### Offset with Reduced V<sub>RFF</sub>

The offset of the LTC1289 has a larger effect on the output code when the A/D is operated with reduced reference voltage. The offset (which is typically a fixed voltage) becomes a larger fraction of an LSB as the size of the LSB is reduced. The typical curve of Unadjusted Offset Error vs Reference Voltage shows how offset in LSBs is related to reference voltage for a typical value of  $V_{OS}$ . For example, a  $V_{OS}$  of 0.1mV which is 0.2LSB with a 2.5V reference becomes 0.4LSB with a 1.25V reference. If this offset is unacceptable, it can be corrected digitally by the receiving system or by offsetting the "–" input to the LTC1289.

#### Noise with Reduced V<sub>REF</sub>

The total input referred noise of the LTC1289 can be reduced to approximately  $200\mu V$  peak-to-peak using a ground plane, good bypassing, good layout techniques and minimizing noise on the reference inputs. This noise is insignificant with a 2.5V reference but will become a larger fraction of an LSB as the size of the LSB is reduced. The typical curve of Noise Error vs Reference Voltage shows the LSB contribution of this  $200\mu V$  of noise.

For operation with a 2.5 reference, the  $200\mu V$  noise is only 0.32LSB peak-to-peak. In this case, the LTC1289 noise will contribute virtually no uncertainty to the output code. However, for reduced references, the noise may become a significant fraction of an LSB and cause undesirable jitter in the output code. For example, with a 1.25V reference, this same  $200\mu V$  noise is 0.64LSB peak-to-peak. This will reduce the range of input voltages over which a stable output code can be achieved by 0.64LSB. In this case averaging readings may be necessary.

This noise data was taken in a very clean setup. Any setup induced noise (noise or ripple on  $V_{CC}$ ,  $V_{REF}$ ,  $V_{IN}$  or  $V^-$ ) will add to the internal noise. The lower the reference voltage to be used, the more critical it becomes to have a clean, noise-free setup.



#### 7. LTC1289 AC Characteristics

Two commonly used figures of merit for specifying the dynamic performance of the A/D's in digital signal processing applications are the Signal-to-Noise Ratio (SNR) and the "effective number of bits (ENOB)." SNR is defined as the ratio of the RMS magnitude of the fundamental to the RMS magnitude of all the nonfundamental signals up to the Nyquist frequency (half the sampling frequency). The theoretical maximum SNR for a sine wave input is given by:

$$SNR = (6.02N + 1.76dB)$$

where N is the number of bits. Thus the SNR is a function of the resolution of the A/D. For an ideal 12-bit A/D the SNR is equal to 74dB. A Fast Fourier Transform (FFT) plot of the

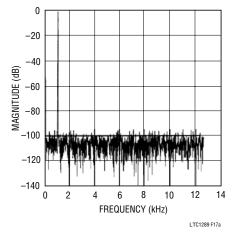


Figure 17a.  $f_{IN} = 1 \text{kHz}$ ,  $f_{S} = 25 \text{kHz}$ , SNR = 72.92 dB

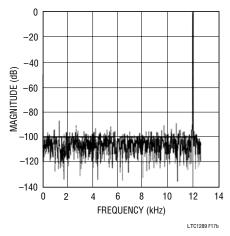


Figure 17b.  $f_{IN} = 12kHz$ ,  $f_{S} = 25kHz$ , SNR = 72.23dB

output spectrum of the LTC1289 is shown in Figures 17a and 17b. The input ( $f_{IN}$ ) frequencies are 1kHz and 12kHz with the sampling frequency ( $f_{S}$ ) at 25kHz. The SNR obtained from the plot are 72.92dB and 72.23dB.

Rewriting the SNR expression it is possible to obtain the equivalent resolution based on the SNR measurement.

$$N = \frac{SNR - 1.76dB}{6.02}$$

This is the so-called effective number of bits (ENOB). For the example shown in Figures 17a and 17b, N=11.8 bits and 11.7 bits, respectively. Figure 18 shows a plot of ENOB as a function of input frequency. The curve shows the A/D's ENOB remain in the range of 11.8 to 11.7 for input frequencies up to  $f_{\rm S}/2$ 

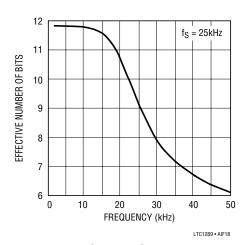


Figure 18. LTC1289 ENOB vs Input Frequency

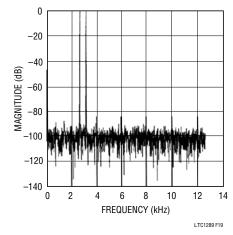


Figure 19.  $f_{IN}1 = 2.6kHz$ ,  $f_{IN}2 = 3.1kHz$ ,  $f_{S} = 25kHz$ 



Figure 19 shows an FFT plot of the output spectrum for two tones applied to the input of the A/D. Nonlinearities in the A/D will cause distortion products at the sum and difference frequencies of the fundamentals and products of the fundamentals. This is classically referred to as intermodulation distortion (IMD).

#### 8. Overvoltage Protection

Applying signals to the analog MUX that exceed the positive or negative supply of the device will degrade the accuracy of the A/D and possibly damage the device. For example this condition would occur if a signal is applied to the analog MUX before power is applied to the LTC1289. Another example is the input source is operating from different supplies of larger value than the LTC1289. These conditions should be prevented either with proper supply sequencing or by use of external circuitry to clamp or current limit the input source. As shown in Figure 20, a  $1k\Omega$  resistor is enough to stand off  $\pm 15V$  (15mA for one only channel). If more than one channel exceeds the supplies than the following guidelines can be used. Limit the current to 7mA per channel and 28mA for all channels. This means four channels can handle 7mA of input current each. Reducing the ACLK and SCLK frequencies from the maximum of 2MHz and 1MHz, respectively (see Typical Peformance Characteristics curves Maximum ACLK Frequency vs Source Resistance and Sample and Hold Acquisition Time vs Source Resistance) allows the use of larger current limiting resistors. Use 1N4148 diode clamps from the MUX inputs to  $V_{CC}$  and  $V^-$  if the value of the series resistor will not allow the maximum clock speeds to be used or if an unknown source is used to drive the LTC1289 MUX inputs.

How the various power supplies to the LTC1289 are applied can also lead to overvoltage conditions. For single supply operation (i.e., unipolar mode), if  $V_{CC}$  and REF<sup>+</sup> are not tied together, then  $V_{CC}$  should be turned on first, then REF<sup>+</sup>. If this sequence cannot be met, connecting a diode from REF<sup>+</sup> to  $V_{CC}$  is recommended (see Figure 21).

For dual supplies (bipolar mode) placing two Schottky diodes from  $V_{CC}$  and  $V^-$  to ground (Figure 22) will prevent power supply reversal from occuring when an input source

is applied to the analog MUX before power is applied to the device. Power supply reversal occurs, for example, if the input is pulled below  $V^-$  then  $V_{CC}$  will pull a diode drop below ground which could cause the device not to power up properly. Likewise, if the input is pulled above  $V_{CC}$  then  $V^-$  will be pulled a diode drop above ground. If no inputs are present on the MUX, the Schottky diodes are not required if  $V^-$  is applied first, then  $V_{CC}$ .

Because a unique input protection structure is used on the digital input pins, the signal levels on these pins can exceed the device  $V_{CC}$  without damaging the device.

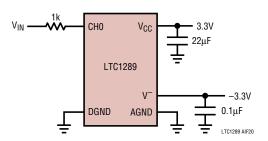


Figure 20. Overvoltage Protection for MUX

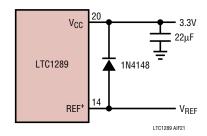


Figure 21.

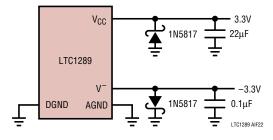


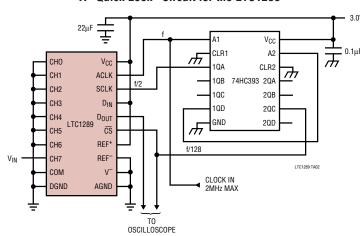
Figure 22. Power Supply Reversal

LINEAR

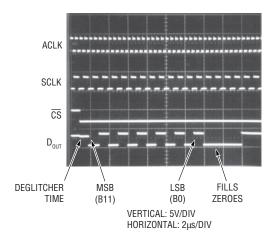
#### A "Quick Look" Circuit for the LTC1289

Users can get a quick look at the function and timing of the LTC1289 by using the following simple circuit. REF+ and  $D_{IN}$  are tied to  $V_{CC}$  selecting a 3V input span, CH7 as a single-ended input, unipolar mode, MSB-first format and 16-bit word length. ACLK is driven by an external clock and SCLK is driven by one half the clock rate.  $\overline{CS}$  is driven at 1/128 the clock rate by the 74HC393 and  $D_{OUT}$  outputs the data. All other pins are tied to a ground plane. The output data from the  $D_{OUT}$  pin can be viewed on an oscilloscope which is set up to trigger on the falling edge of  $\overline{CS}$ .

#### A "Quick Look" Circuit for the LTC1289



# Scope Trace of LTC1289 "Quick Look" Circuit Showing A/D Output of 0101010101010 (555<sub>HFX</sub>)

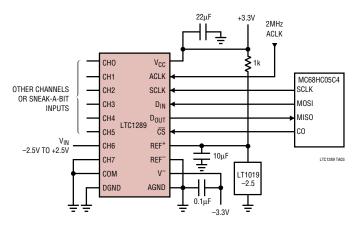


#### SNEAK-A-BIT™

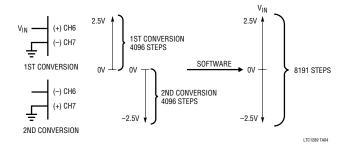
The LTC1289's unique ability to software select the polarity of the differential inputs and the output word length is used to achieve one more bit of resolution. Using the circuit below with two conversions and some software, a 2's complement 12-bit + sign word is returned to memory inside the MPU. The MC68HC05C4 was chosen as an example, however, any processor that operates at 3.3V could be used.

Two 12-bit unipolar conversions are performed: the first over a 0V to 2.5V span and the second over a 0V to -2.5V span (by reversing the polarity of the inputs). The sign of the input is determined by which of the two spans contained it. Then the resulting number (ranging from -4095 to +4095 decimal) is converted to 2's complement notation and stored in RAM.

#### **SNEAK-A-BIT Circuit**



#### **SNEAK-A-BIT**



SNEAK-A-BIT is a trademark of Linear Technology Corp.



#### **SNEAK-A-BIT Code**

D<sub>OUT</sub> from LTC1289 in MC68HC05C4 RAM

### Sign

Location \$77

B12 B11 B10 B9 B8 B7 B6 B5

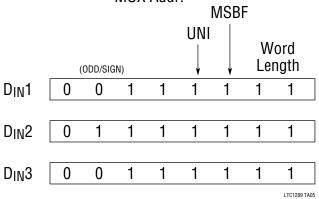
LSB

Location \$87

B4 B3 B2 B1 B0 filled with 0s

# D<sub>IN</sub> words for LTC1289

MUX Addr.



#### SNEAK-A-BIT Code for the LTC1289 Using the MC68HC05C4

M	NEMOI	VIC	DESCRIPTION
	LDA	#\$50	Configuration data for SPCR
	STA	\$0A	Load configuration data into \$0A
	LDA	#\$FF	Configuration data for port C DDR
	STA	\$06	Load configuration data into port C DDR
	BSET	0, \$02	Make sure $\overline{\text{CS}}$ is high
	JSR	READ -/+	Dummy read configures LTC1289 for
			next read
	JSR	READ +/-	Read CH6 with respect to CH7
	JSR	READ -/+	Read CH7 with respect to CH6
	JSR	CHK SIGN	Determines which reading has valid
			data, converts to 2's complement and
			stores in RAM
READ -/+:		#\$3F	Load D <sub>IN</sub> word for LTC1289 into ACC
	JSR	TRANSFER	Read LTC1289 routine
	LDA	\$60	Load MSBs from LTC1289 in ACC
	STA	\$71	Store MSBs in \$71
	LDA	\$61	Load LSBs from LTC1289 in ACC
	STA	\$72	Store LSBs in \$72
	RTS		Return

#### SNEAK-A-BIT Code for the LTC1289 Using the MC68HC05C4

M	NEMOI	NIC	DESCRIPTION
READ +/-:	LDA	#\$7F	Load D <sub>IN</sub> word for LTC1289 into ACC
	JSR	TRANSFER	Read LTC1289 routine
	LDA		Load MSBs from LTC1289 into ACC
	STA		Store MSBs in \$73
	LDA	\$61	Load LSBs from LTC1289 into ACC
	STA		Store LSBs in \$74
	RTS		Return
TRANSFER:	BCLR	0, \$02	CS goes low
	STA	\$0C	Load D <sub>IN</sub> into SPI. Start transfer
L00P 1:	TST	\$0B	Test status of SPIF
	BPL	L00P 1	Loop to previous instruction if not done
	LDA	\$0C	Load contents of SPI data reg into ACC
	STA	\$0C	Start next cycle
	STA	\$60	Store MSBs in \$60
L00P 2:	TST	\$0B	Test status of SPIF
	BPL		Loop to previous instruction if not done
		0, \$02	CS goes high
	LDA		Load contents of SPI data reg into ACC
	STA	\$61	Store LSBs in \$61
	RTS		Return
CHK SIGN:	LDA		Load MSBs of +/- read into ACC
	ORA	*	Or ACC (MSBs) with LSBs of +/- read
	BEQ	MINUS	If result is 0 goto minus
	CLC	<b>470</b>	Clear carry
	ROR		Rotate right \$73 through carry
	ROR		Rotate right \$74 through carry
	LDA		Load MSBs of +/- read into ACC
	STA		Store MSBs in RAM locations \$77
	LDA		Load LSBs of +/- read into ACC
	STA	\$87	Store LSBs in RAM location \$87 Goto end of routine
MINITIO	BRA	END	
MINUS:	CLC ROR	¢71	Clear carry
	ROR		Shift MSBs of -/+ read right Shift LSBs of -/+ read right
	COM		1's complement of MSBs
	COM		1's complement of LSBs
	LDA		Load LSBs into ACC
	ADD		Add 1 to LSBs
	STA	#\$01 \$72	Store ACC in \$72
	CLRA		Clear ACC
	ADC	\$71	Add with carry to MSBs. Result in ACC
	STA	\$71	Store ACC in \$71
	STA	\$77	Store MSBs in RAM locations \$77
	LDA	\$72	Load LSBs in ACC
END:		<del>+0</del> 1	Return
END:	STA RTS	\$87	Store LSBs in RAM location \$87



#### **Power Shutdown**

For battery-powered applications it is desirable to keep power dissipation at a minimum. The LTC1289 can be powered down when not in use reducing the supply current from a nominal value of 1mA to typically 1 $\mu$ A (with ACLK turned off). See the Curve for Supply Current (Power Shutdown) vs ACLK if ACLK cannot be turned off when the LTC1289 is powered down. In this case the supply current is proportional to the ACLK frequency and is independent of temperature until it reaches the magnitude of the supply current attained with ACLK turned off.

As an example of how to use this feature let's add this to the previous application, SNEAK-A-BIT. After the CHK SIGN subroutine call insert the following:

JSR CHK SIGN

Determines which reading has valid data, converts to 2's complement

and stores in RAM

JSR SHUTDOWN

LTC1289 power shutdown routine

The actual subroutine is:

SHUTDOWN: LDA #\$3D

Load D<sub>IN</sub> word for

LTC1289 into ACC
JSR TRANSFER Read LTC1289 routine

RTS Return

To place the device in power shutdown the word length bits are set to WL1 = 0 and WL0 = 1. The LTC1289 is powered up on the next request for conversion and it's ready to digitize an input signal immediately.

#### **Power Shutdown Timing Considerations**

After power shutdown has been requested, the LTC1289 is powered up on the next request for a conversion. This request can be initiated either by bringing  $\overline{\text{CS}}$  low or by starting the next cycle of SCLKs if  $\overline{CS}$  is kept low (see Figures 3 and 4). When the SCLK frequency is much slower than the ACLK frequency a situation can arise where the LTC1289 could power down and then prematurely power back up. Power shutdown begins at the negative going edge of the 10th SCLK once it has been requested. A dummy conversion is executed and the LTC1289 waits for the next request for conversion. If the SCLKs have not finished once the LTC1289 has finished its dummy conversion, it will recognize the next remaining SCLKs as a request to start a conversion and power up the LTC1289 (see Figure 23). To prevent this, bring either  $\overline{CS}$ high at the 19th SCLK (Figure 24) or clock out only 10 SCLKs (Figure 25) when power shutdown is requested.

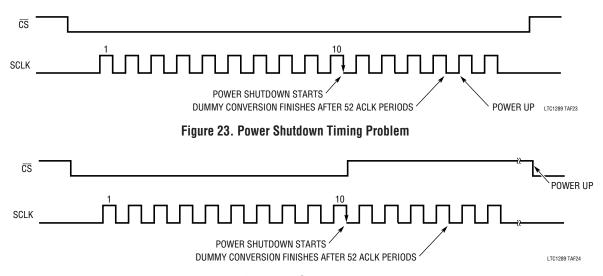


Figure 24. Power Shutdown Timing





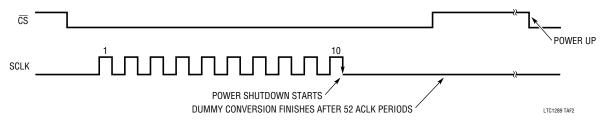
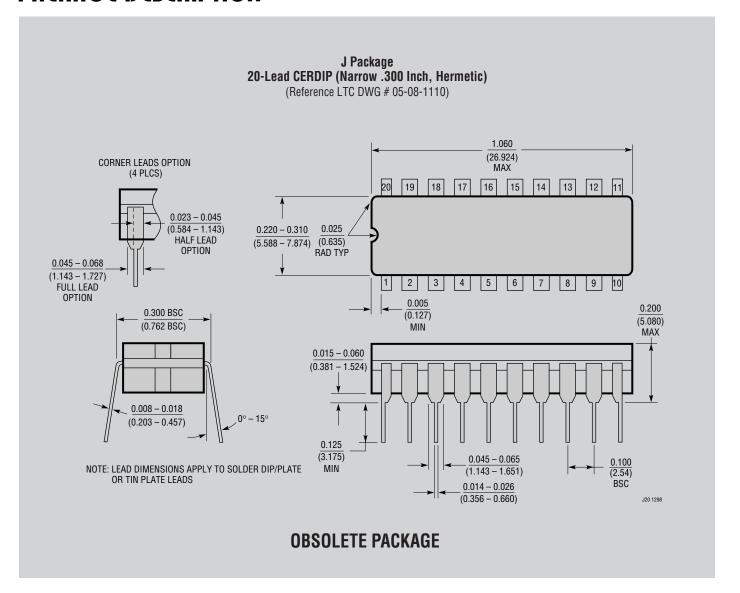


Figure 25. Power Shutdown Timing

# PACKAGE DESCRIPTION

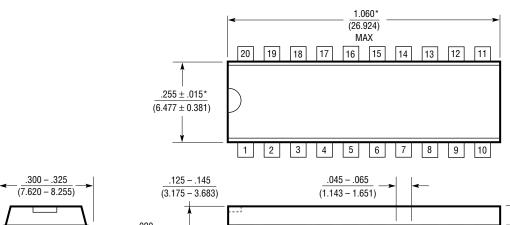


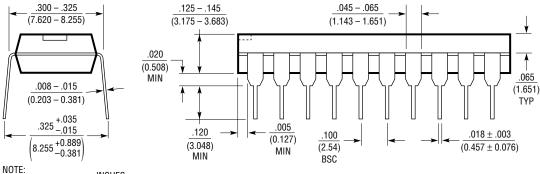
N20 0405

# PACKAGE DESCRIPTION

#### N Package 20-Lead PDIP (Narrow .300 Inch)

(Reference LTC DWG # 05-08-1510)



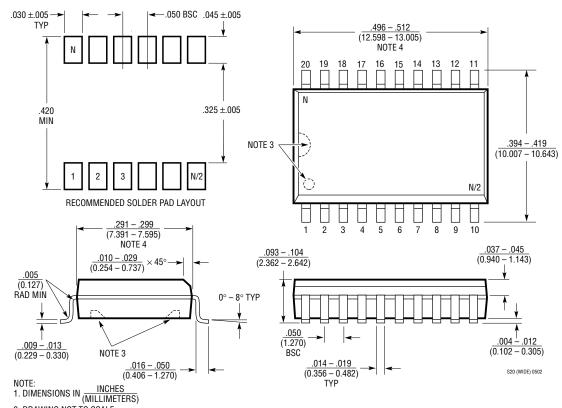


NOTE:
1. DIMENSIONS ARE INCHES
MILLIMETERS
\*THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010 INCH (0.254mm)

### PACKAGE DESCRIPTION

#### SW Package 20-Lead Plastic Small Outline (Wide .300 Inch)

(Reference LTC DWG # 05-08-1620)



- 2. DRAWING NOT TO SCALE
- 3. PIN 1 IDENT, NOTCH ON TOP AND CAVITIES ON THE BOTTOM OF PACKAGES ARE THE MANUFACTURING OPTIONS.
- THE PART MAY BE SUPPLIED WITH OR WITHOUT ANY OF THE OPTIONS 4. THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
- MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .006" (0.15mm)

# **RELATED PARTS**

PART NUMBER	DESCRIPTION	COMMENTS
LTC1285/LTC1288	1-/2-Channel, 3V, Micropower 12-Bit ADC	Autoshutdown, SO-8 Package
LTC1290	8-Channel Configurable, 5V, 12-Bit ADC	Pin-Compatible with LTC1289
LTC1391	Serial-Controlled 8-to-1 Analog Multiplexer	Low R <sub>ON</sub> , Low Power, 16-Pin SO and SSOP Package
LTC1401	3V, 12-Bit, 200ksps Serial ADC	15mW, Internal Reference, SO-8 Package
LTC1448	Dual 12-Bit V <sub>OUT</sub> DACs in SO-8 Package	0.5LBS DNL, 3V to 5V Supply, Swings 0V to V <sub>REF</sub>
LTC1454/LTC1454L	Dual 12-Bit V <sub>OUT</sub> DACs in SO-16 Package	5V/3V, Buffered Rail-to-Rail Output, 0.5LSB DNL
LTC1458/LTC1458L	Quad 12-Bit V <sub>OUT</sub> DACs	5V/3V, Buffered Rail-to-Rail Output, 0.5LSB DNL
LTC1594/LTC1598L	4-/8-Channel, 3V Micropower 12-Bit ADC	Low Power, Small Size
LTC1852/LTC1853	10-Bit/12-Bit, 8-Channel, 400ksps ADCs	3V or 5V, Programmable MUX and Sequencer
LTC2404/LTC2408	24-Bit, 4-/8-Channel, No Latency $\Delta\Sigma$ ADC	4ppm INL, 10ppm Total Unadjusted Error, 200μA
LTC2424/LTC2428	20-Bit, 4-/8-Channel, No Latency $\Delta\Sigma$ ADC	1.2ppm Noise, 8ppm INL, Pin Compatible with LTC2404/LTC2408

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LTC1289CCSW#PBF LTC1289BCSW#PBF